



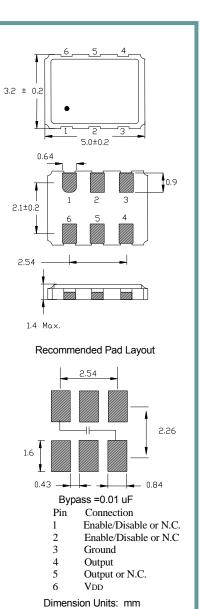
#### Product Features

Small Surface Mount Package Low RMS Phase Jitter Frequencies to 1500 MHz Pb Free/ RoHS Compliant Leadfree Processing

#### Applications

xDSL Broadcast video Wireless Base Stations Sonet /SDH WiMAX/WLAN Server and Storage Ethernet/LAN/WAN Optical modules Clock and data recovery FPGA/ASIC Backplanes GPON

Frequency LVCMOS LVPECL	10 MHz to 250 MHz 10 MHz to 1500 MHz	
LVDS	10 MHz to 1500 MHz	
Output Level		
LVCMOS LVPECL LVDS	VOH=90% VDD min., VOL=10 % VDD max. VOH=VDD-1.03V max. (Nom. Load), VOL=VDD-1.6V max. (Nom. Load) VOD=(Diff. Output) 350mV Typ.	
Duty Cycle		
LVCMOS LVPECL	50% ±5% @ 50%VDD 50% ±5% @ 50%*	
LVDS	50% ±5% @ 50%*	
Rise / Fall Time	2.0 === ==== (000/ (400/ )*	
LVCMOS LVPECL	3.0 ns max. (90%/10%)* 0.6 ns max. (80%/20%)*	
LVDS	0.6 ns max. (80%/20%)*	
Output Load		
LVPECL	15pF 50 Ω to VDD - 2.0 VDC	
LVDS	RL=100 $\Omega$ /CL=10pF	
Frequency Stability	See Table Below	
Supply Voltage	3.3 VDC ± 10%, 2.5VDC ± 5%	
Current	LVCMOS = 45 mA max., LVPECL = 65 mA max. LVDS = 35 mA max.	
Phase Jitter (RMS) At 12kHz to 20 MHz	0.5 ps typical	
Operating Temp. Range	See Table Below	
Storage	-40° C to +100° C	



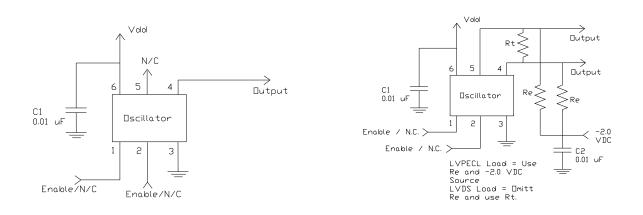
Part Number Guide Sample Part Number: ISM74-31A9H2-155.520 Package Input Operating Stability Output Enable / Disable Complimentary Frequency Ouput (Pin 5) \*\* Voltage Temperature (in ppm) 3 = 3.3V  $1 = 0^{\circ} \text{ C}$  to  $+70^{\circ} \text{ C}$ F = ±20 3 = LVCMOS H = Enable (Pin 1) 1 = N.C. K = Enable (Pin 2) 2 = Output 6 = 2.5V  $3 = -20^{\circ} \text{ C}$  to  $+70^{\circ} \text{ C}$ 8 = LVDS A = ±25 ISM74 -155.520 MHz  $2 = -40^{\circ} \text{ C}$  to  $+85^{\circ} \text{ C}$ B = ±50 9 = LVPECL

NOTE: A 0.01 µF bypass capacitor is recommended between V<sub>DD</sub> (pin 6) and GND (pin 3) to minimize power supply noise. \* Measured as percent of waveform. \*\* Available on LVDS and LVPECL ouput only.

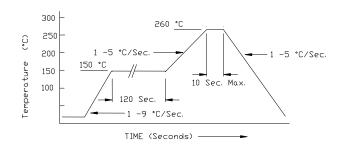




# **Typical Application:**



## Pb Free Solder Reflow Profile:

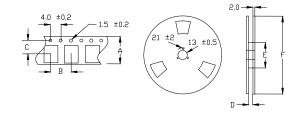


\*Units are backward compatible with 240C reflow processes

## Package Information:

MSL = N.A. (package does not contain plastic, storage life is unlimited under normal room conditions). Termination = e4 (Au over Ni over W base metalization).

### Tape and Reel Information:



Quantity per Reel	1000
A	16 +/3
В	8 +/2
C	7.5 +/2
D	17.5 +/-1
E	50 / 60 / 80
F	180 / 250

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#### **Environmental Specifications**

Thermal Shock	MIL-STD-883, Method 1011, Condition A
Moisture Resistance	MIL-STD-883, Method 1004
Mechanical Shock	MIL-STD-883, Method 2002, Condition B
Mechanical Vibration	MIL-STD-883, Method 2007, Condition A
Resistance to Soldering Heat	J-STD-020C, Table 5-2 Pb-free devices (except 2 cycles max)
Hazardous Substance	Pb-Free / RoHS / Green Compliant
Solderability	JESD22-B102-D Method 2 (Preconditioning E)
Terminal Strength	MIL-STD-883, Method 2004, Test Condition D
Gross Leak	MIL-STD-883, Method 1014, Condition C
Fine Leak	MIL-STD-883, Method 1014, Condition A2, R1=2x10-8 atm cc/s
Solvent Resistance	MIL-STD-202, Method 215
Solvent Resistance	MIL-STD-202, Method 215

#### Marking

Line 1: ILSI and Date Code (YWW) Line 2: Frequency

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